

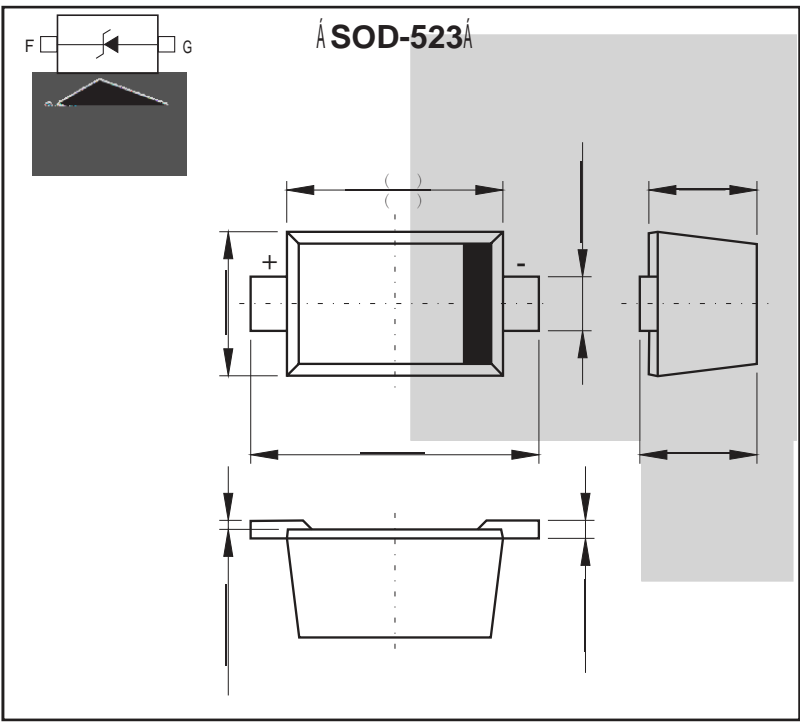
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: 95H I F9G''

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5DD@=75H-CBG

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A5L-A I A'F5H-B ; G'5B8'7 < 5F57H9F-GH-7G

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Parameter	Symbol	Limits	Unit
IEC 61000-4-2 (ESD) Air Contact		30	kV
ESD voltage per human body model per machine model		16 400	kV V
Total power dissipation on FR-5 board(Note 1)	P _D	150	mW
Junction and Storage temperature range	T _j , T _{stg}	-55 to +150	
Thermal Resistance Junction-to Ambient	R _{JA}	833	/W
Lead solder temperature range (10 Second Duration)	T _L	260	

Note 1.FR-5=1.0*0.75*0.62in

F5H=B ; G 5B8 7 < 5F57H9F=GH=7 7 I FJ9G

9 YWnf] WU ' GdYVYZ] WWh] cb' çVcEMG í »ÔÁ~ }| ^••Á [c@^! , î•^Á•] ^&î-î^âD

Device	Device Marking	V_{RWM}	I_R (A)	V_{BR} (V)		I_T	$V_C@$	I_{PP}	$V_C@$	P_{PK}	C (pF)
		(V)	@ V_{RWM}	Min.	Max.	mA	$I_{PP}=5A$	Max I_{PP}	Max I_{PP}	W	pF
ESD5V0D5	ZF	5.0	0.08	6.2	7.3	1.0	11.6	9.4	18.6	174	80

PACKAGE INFORMATION

Device	Package	Shipping
ESD5V0D5	SOD-523	000/Tape&Reel

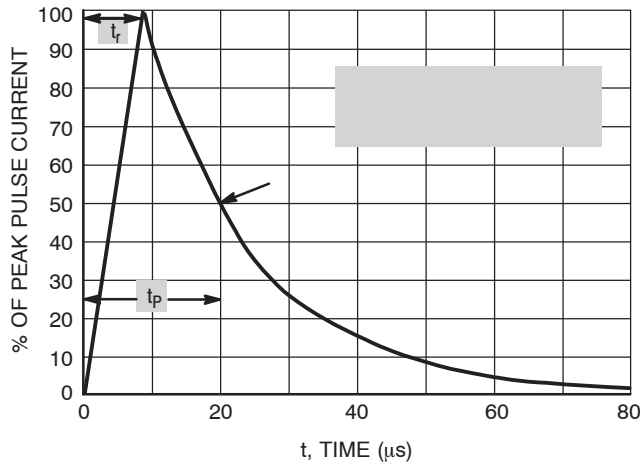


Figure 1. 8 x 20 µs Pulse Waveform